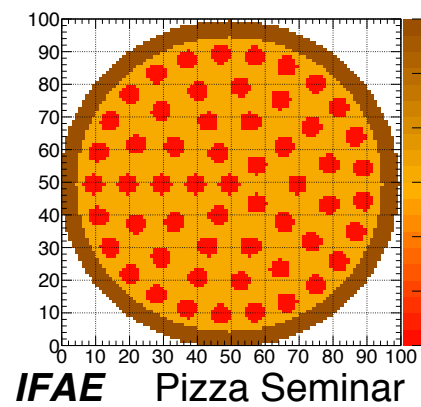


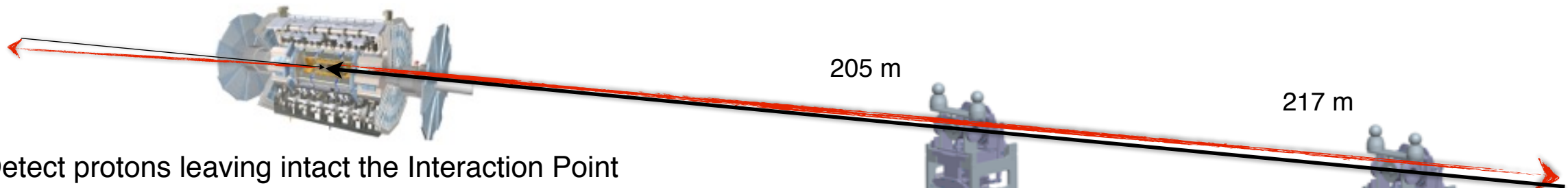
AFP: A new LHC detector made in Barcelona

I. López Paz



Astonishingly Fast Project (AFP)

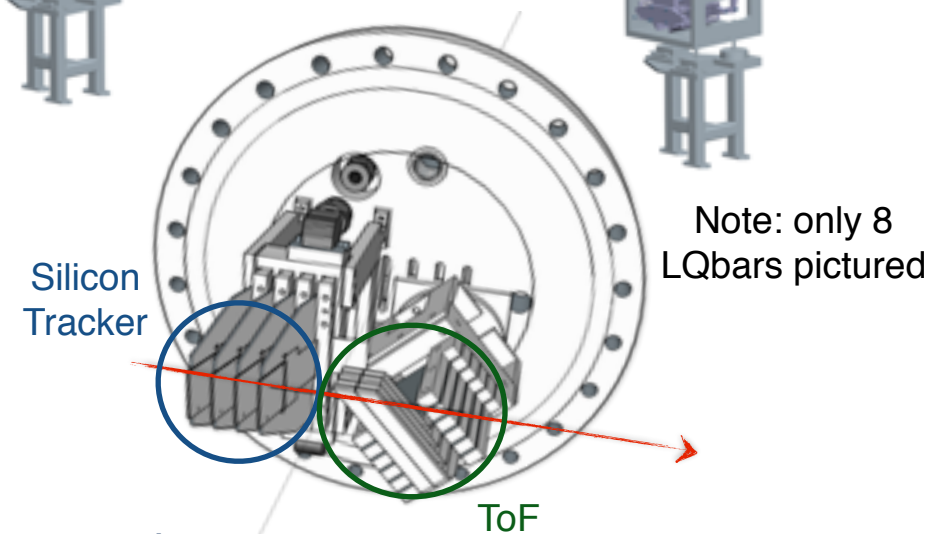
ATLAS Forward Protons (AFP)



Motivation: Detect protons leaving intact the Interaction Point

Detectors in AFP

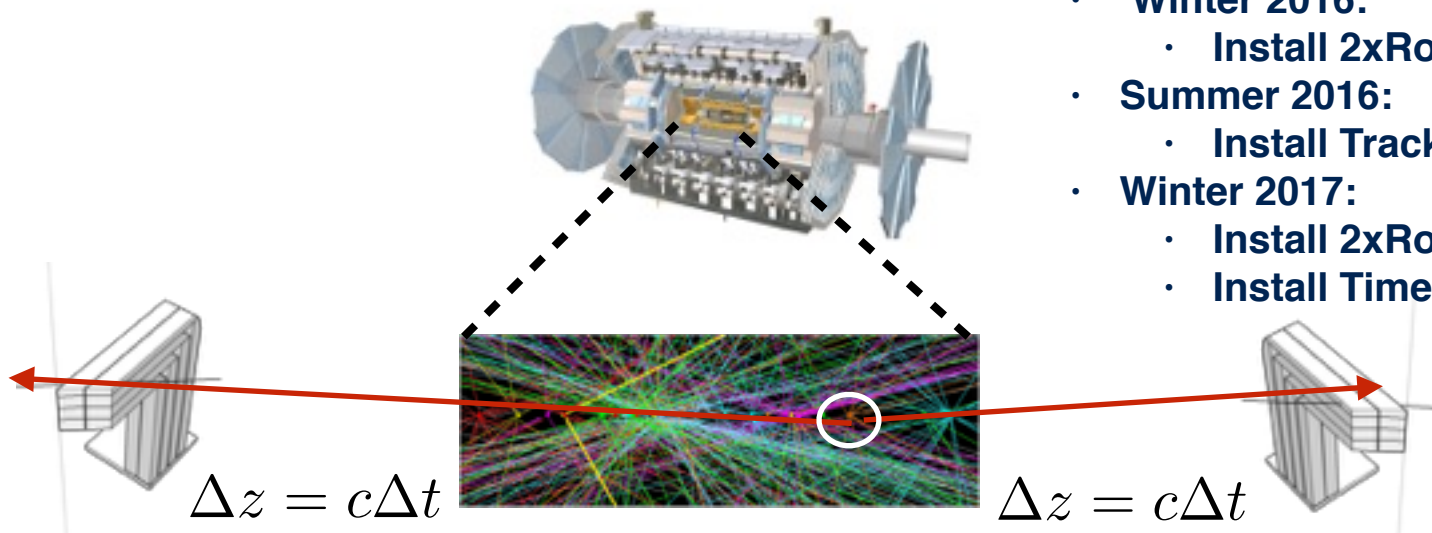
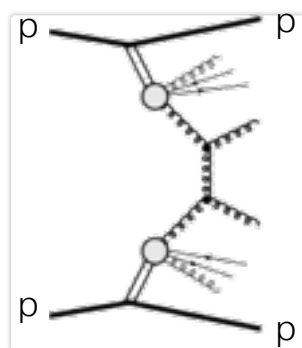
- **3D Silicon Tracker:** 4 planes per station in all stations
 - Reconstruct transverse momentum and proton energy loss
- **Time-Of-Flight:** 16 L-shaped Quartz bars (LQbars) per side
 - Determine position of primary vertex of the proton (pile-up removal)



Roman Pots: Move detectors ~3 mm from the beam

AFP schedule (Dec. 2015)

- **Winter 2016:**
 - Install 2xRoman Pots in one side of ATLAS
- **Summer 2016:**
 - Install Tracker in Roman Pots
- **Winter 2017:**
 - Install 2xRoman Pots in other side of ATLAS with tracker
 - Install Time-of-Flight detectors



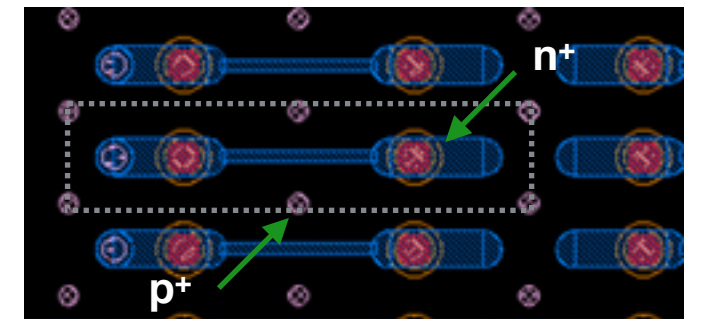
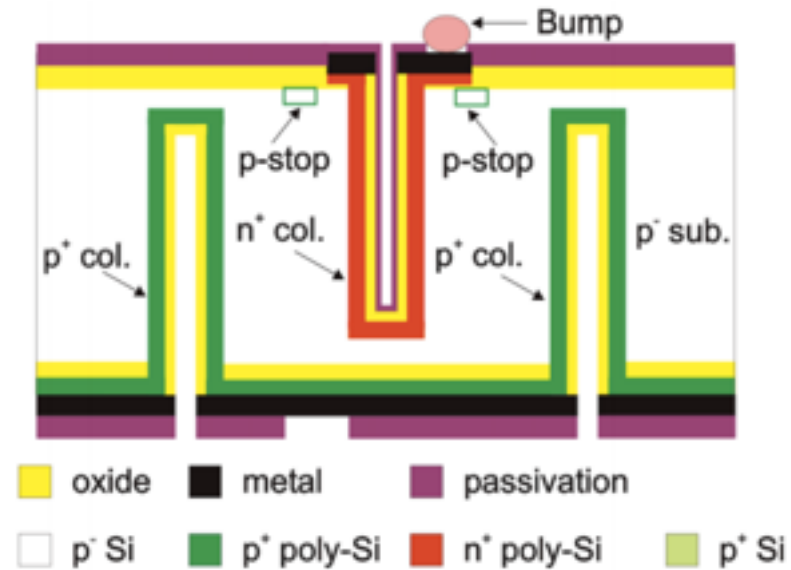
AFP 3D silicon detectors

- **Column-like electrodes**

- Inter-electrode distance ($\sim 67 \mu\text{m}$) de-coupled from detector thickness ($230 \mu\text{m}$)
 - **Lower voltage** for full efficiency ($< 10 \text{ V}$) before irradiation
 - Shorter drift distance \rightarrow Low trapping probability \rightarrow **Radiation hard**

- **2nd use of 3D detectors in HEP**

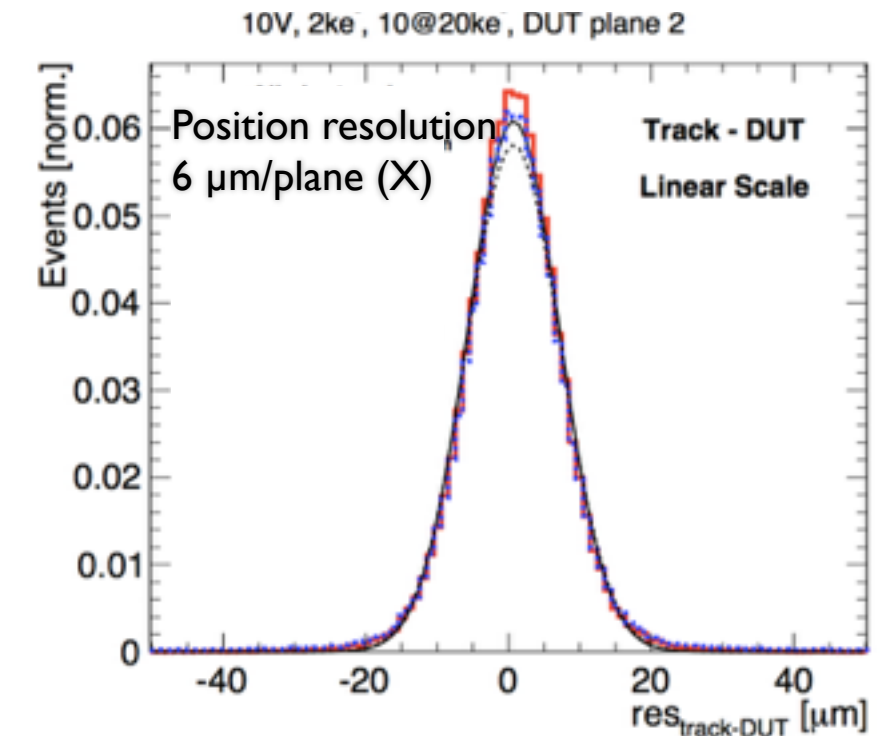
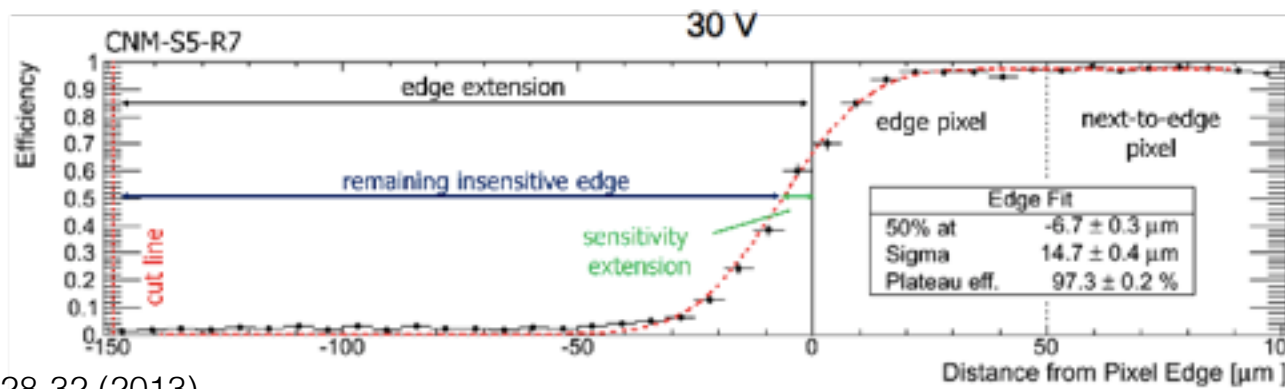
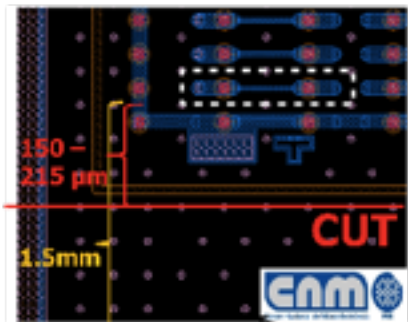
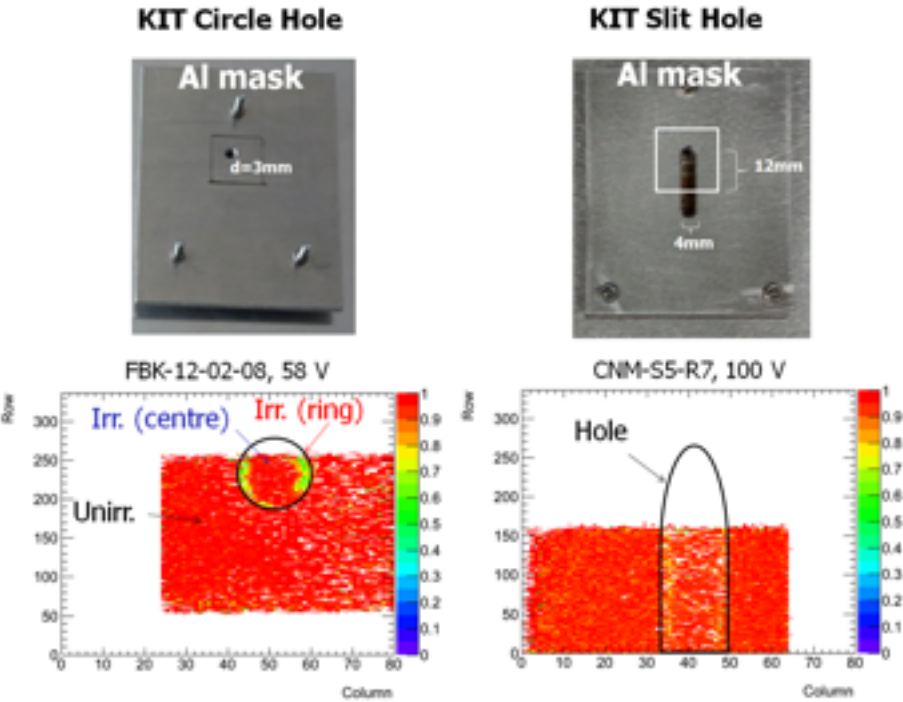
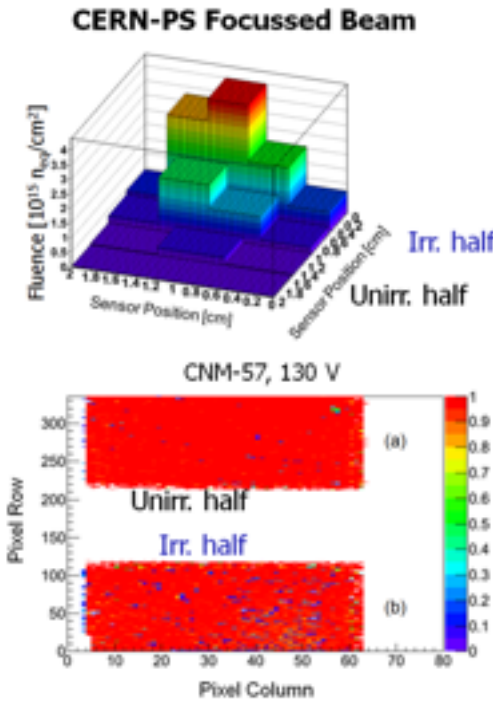
- First use in ATLAS Insertable B-Layer (IBL, 2014)
- Profit from previous experience with IBL sensors (FE-I4) **IFAE was the 3D detector expert in IBL**



Characterize slim-edged 3D sensors with FE-I4 chip for AFP in testbeams

Test-beam characterization for AFP (2012-2014)

- **Radiation hardness**
 - High efficiency after non-uniform irradiation
- **Slim-edge efficiency**
 - Slim-edged sensors down to $\sim 180 \mu\text{m}$
 - Efficient up to the last active pixel
- **Measured position resolution**
 - $6 \mu\text{m}$ resolution per plane



S. Grinstein et al, NIMA 730 28-32 (2013)
 J. Lange et al, JINST 10 C03031 (2015)
 I. Lopez et al, IEEE ANIMA2015 Conf. Proc.

3D FE-I4 detectors proven suitable for AFP

Tracker and ToF integration test-beams (2014-2016)

TRACKING: 5 FE-I4 3D Pixel Detectors

- IBL style (by CNM/FBK), IBL spares (not best quality)



Trigger: Pixel Plane Coincidence

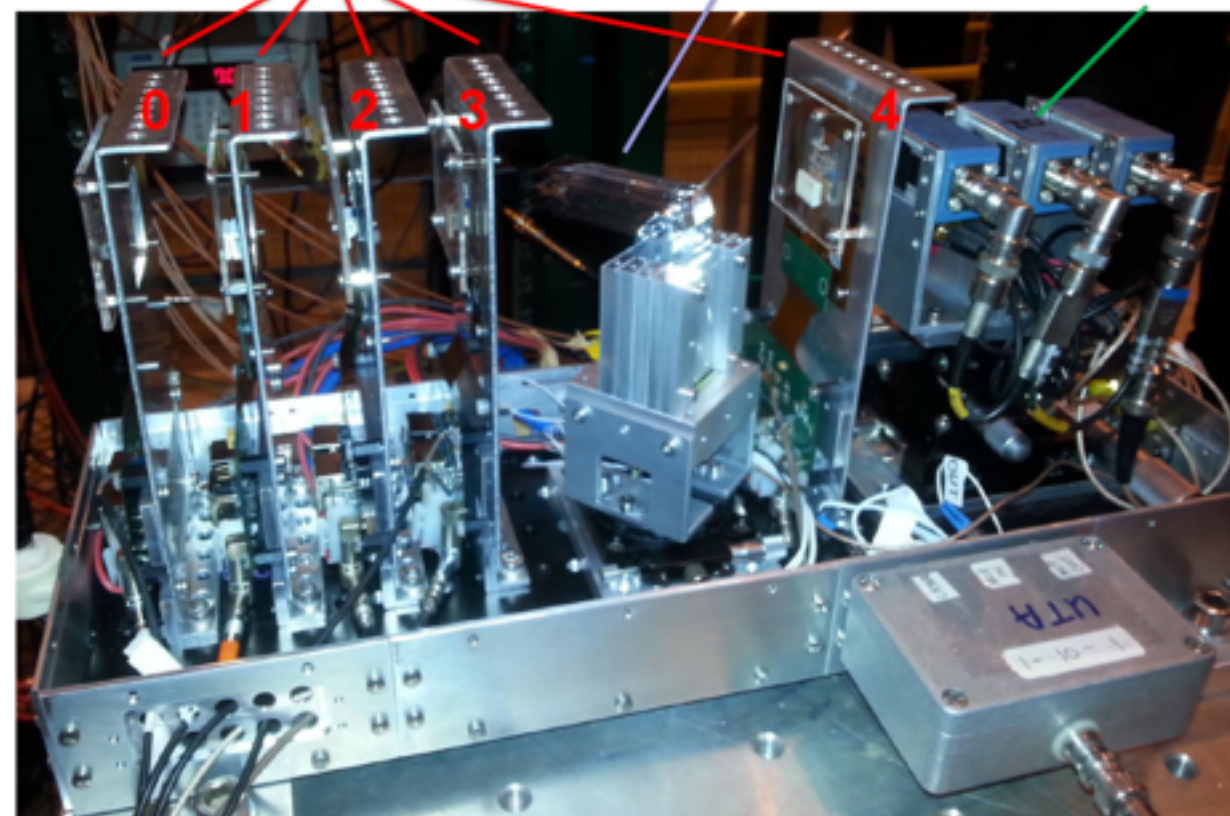
- Logic by HitBus chip developed for ATLAS-DBM



Tracker: 4+1 3D FEI4 pixels
→ trigger: 0 & 3 & 4

Timing: Quartic
4 trains of 2 LQbars

Quartz+SiPM
fast timing reference
(not for final AFP detector)



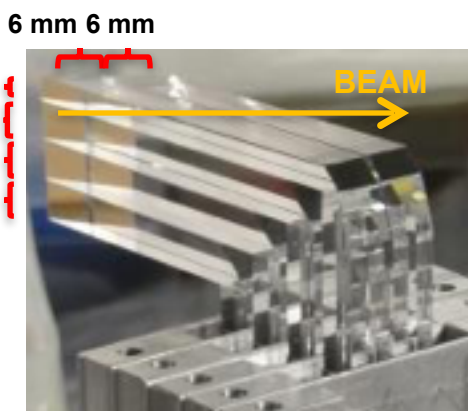
READOUT: RCE



TIMING: 4 rows of trains of 2 LQbars

- Oriented at Cherenkov angle of 48°

- 3 mm Train 1
- 5 mm Train 2
- 5 mm Train 3
- 5 mm Train 4



Signal chain

- 4x4-pixel MCP-PMT
- PreAmp
- Constant Fraction Discriminators (CFD)
- High-Precision Time-to-Digital (HPTDC)



Strong participation of IFAE:

- Testbeam experts
- Tracker experts
- Testbeam coord. (J. Lange)

Successful integration test beam

→ AFP approved for installation (Summer 2015)

Presented in ATLAS weekly (J. Lange)
<https://indico.cern.ch/event/286492/>

ATL-COM-UPGRADE-2015-010
Submitted to JINST

AFP tracker module production: Overview

Chip



Sensor



Carrier card



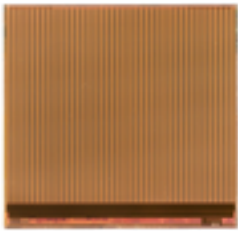
Flex (~Cable)



Full module production at IFAE

AFP tracker module production: Overview

Chip



Sensor



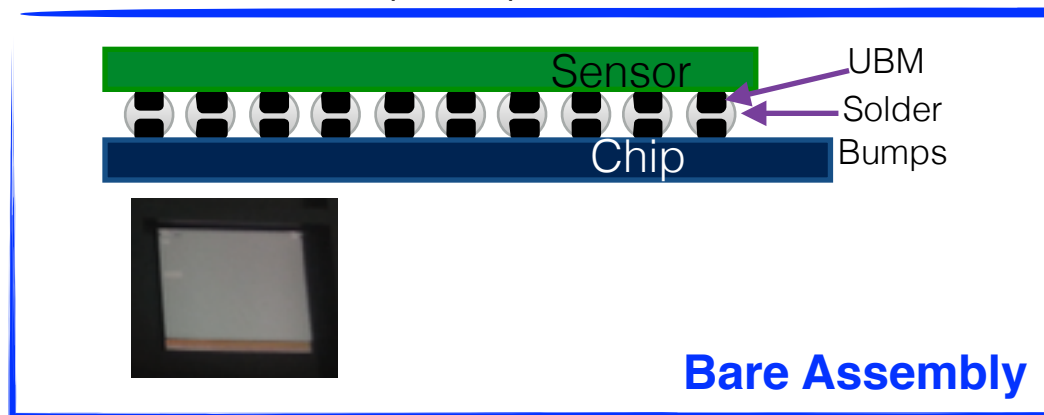
Carrier card



Flex (~Cable)



Flip-Chip



Full module production at IFAE

AFP tracker module production: Overview

Chip



Sensor



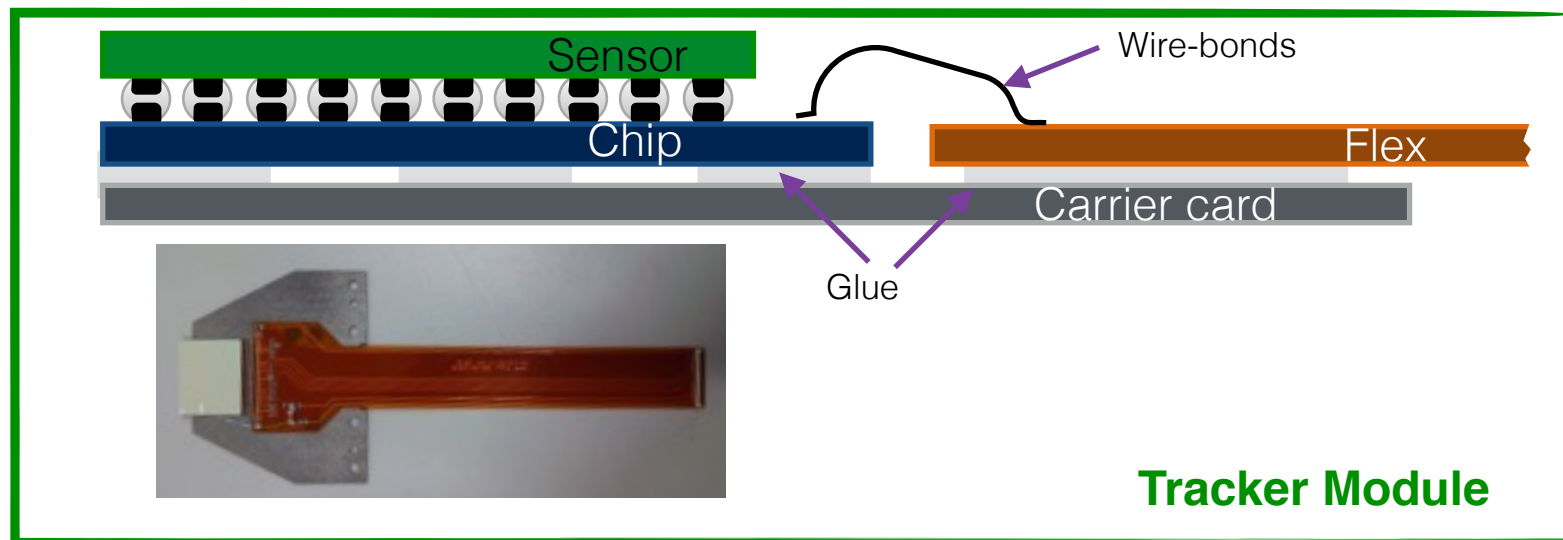
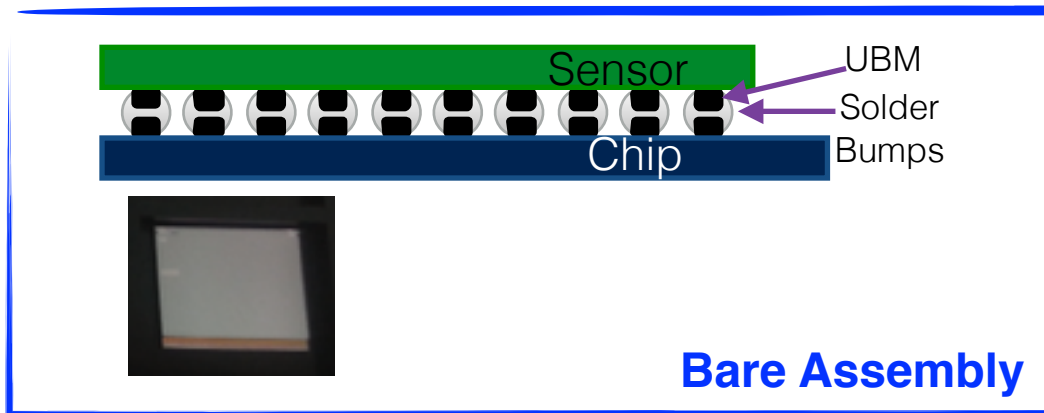
Carrier card



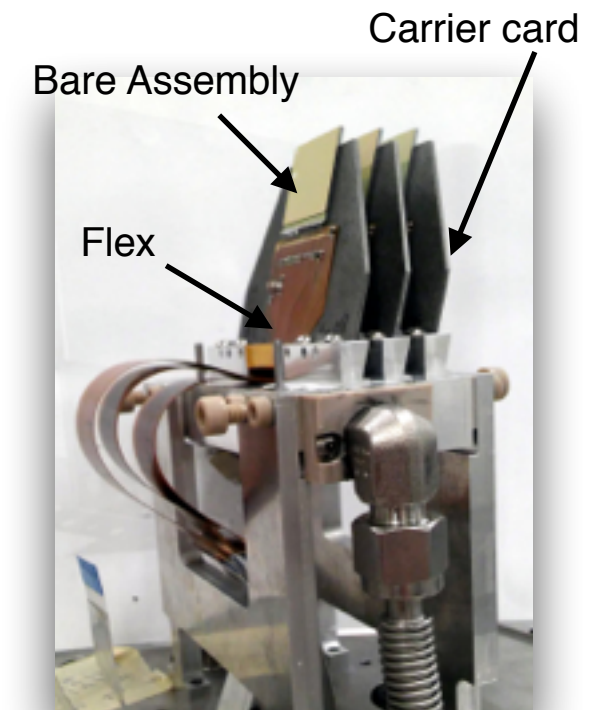
Flex (~Cable)



Flip-Chip



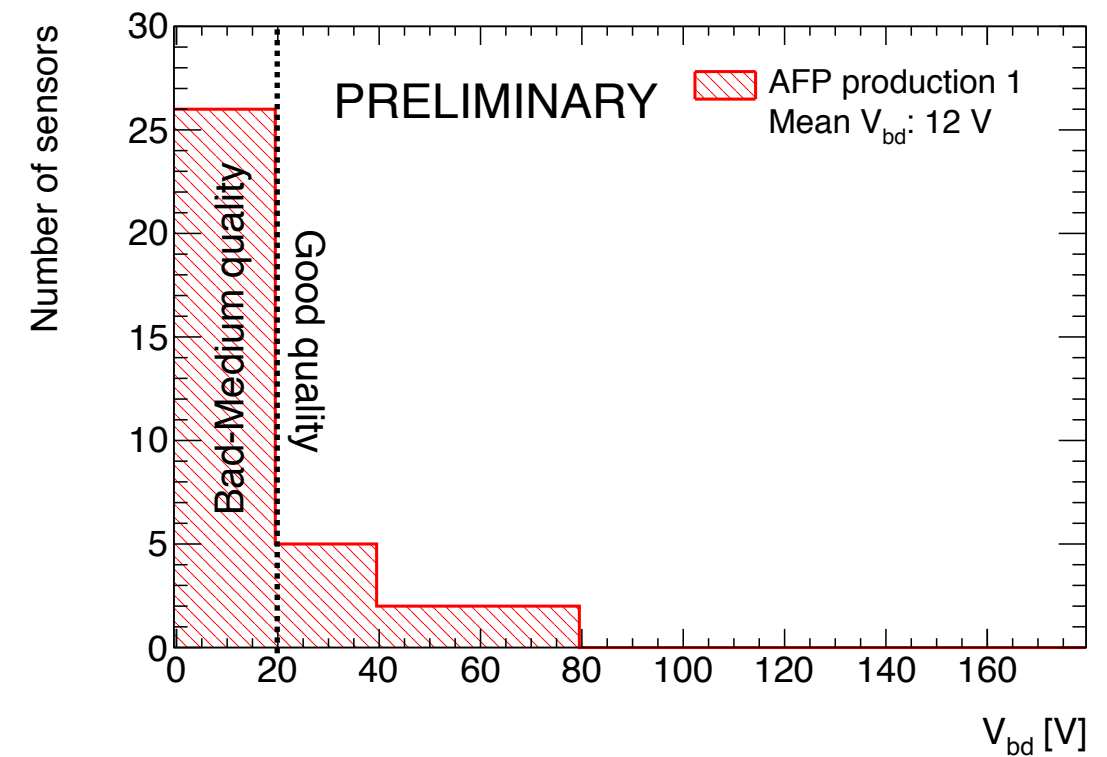
Full module production at IFAE



Sensor Production

- **First CNM production** (January 2015) for AFP had low yield:
 - 40 sensors produced in total (5 wafers)
 - 5 broken sensors
 - 19+7 bad-medium quality IV: $V_{BD} < 20$ V
 - 9 good quality IV: $V_{BD} > 20$ V

Sufficient for first installation (YETS 2015-2016)



Production run	Wafer Yield	Good Wafers	Sensor Yield	Good Sensors
AFP 1	38 %	5	23 %	9

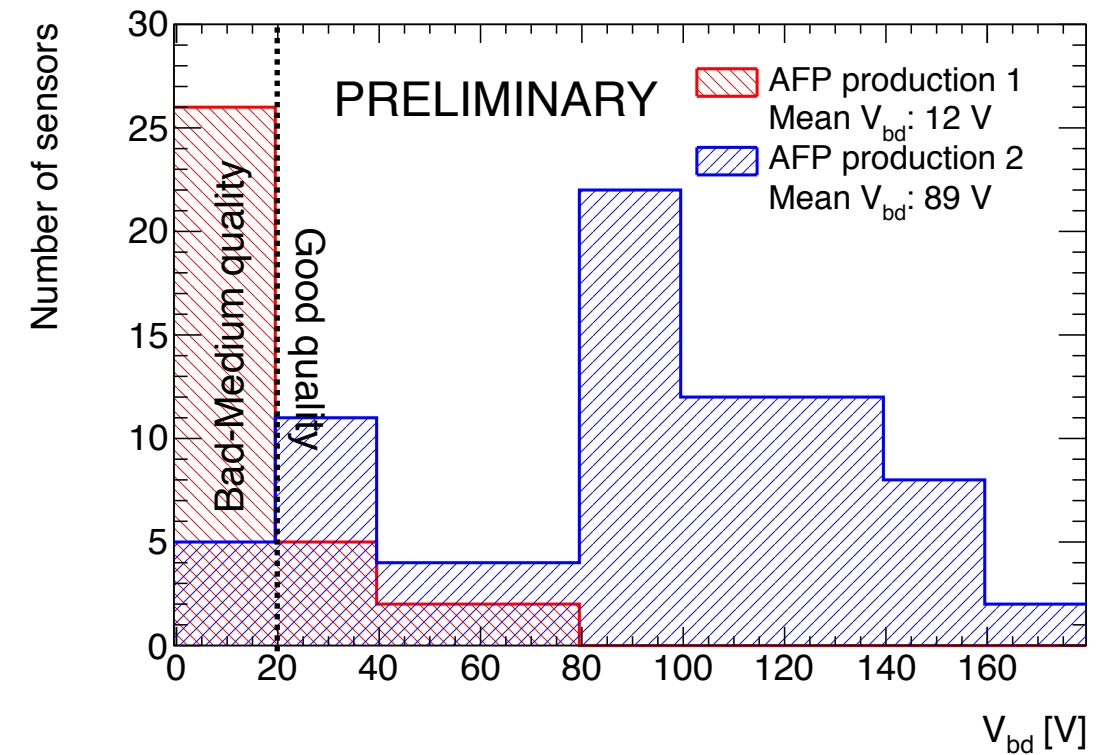
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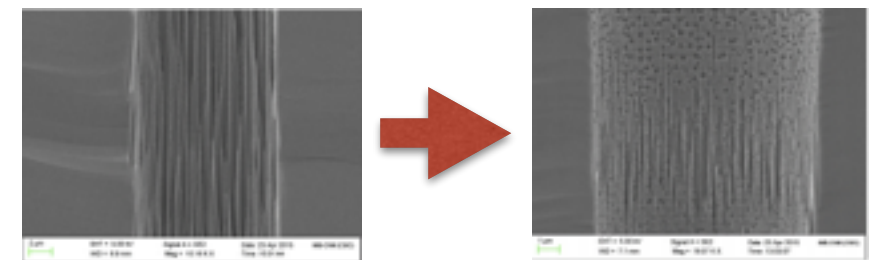
Sufficient for first installation (one ATLAS side)

- **Second CNM production** (April 2016):
 - 80 sensors produced in total (10 wafers)
 - 5 bad quality: $V_{BD} < 20$ V
 - 75 good quality: $V_{BD} > 20$ V
- } **Optimization of column-etching process at CNM**

Second production for winter 2016-2017 installation



Production run	Wafer Yield	Good Wafers	Sensor Yield	Good Sensors
AFP 1	38 %	5	23 %	9
AFP 2	83 %	10	94 %	75



Side-walls damage reduced of columns

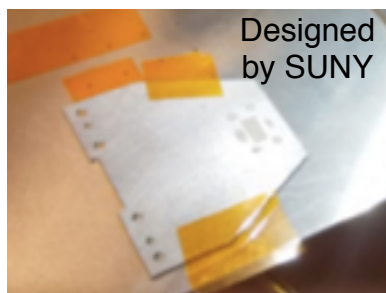
Bare Assembly and Tracker Module Production

- **Bare Assembly:** Sensor flip-chipped to FE-I4 chip
 - Select sensor based on IV behavior at “wafer” level to be flip-chipped
- **Tracker Module:** Bare Assembly + carrier card + Flex
 - Bare Assembly is glued onto the carrier card with alignment marks
 - Flex also glued onto carrier card
 - Chip is wire-bonded to Flex

Production Step	Total	Good	Yield
Bump Bonding	22	21	95 %
Assembly	17	17	100 %

Note: includes modules produced after installation

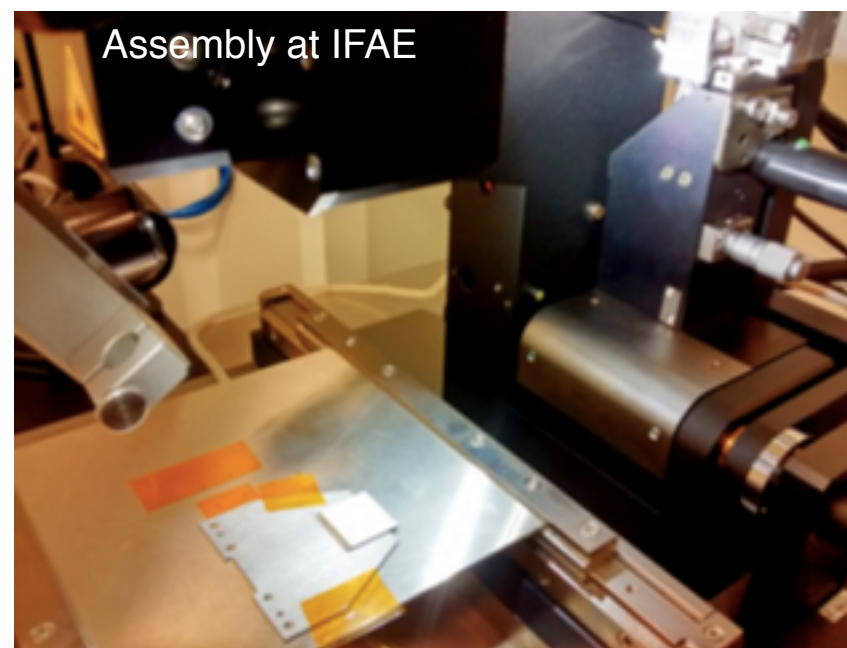
Bump-bonding and Assembly at IFAE (Mokhtar, Jorge G. Eric P.)



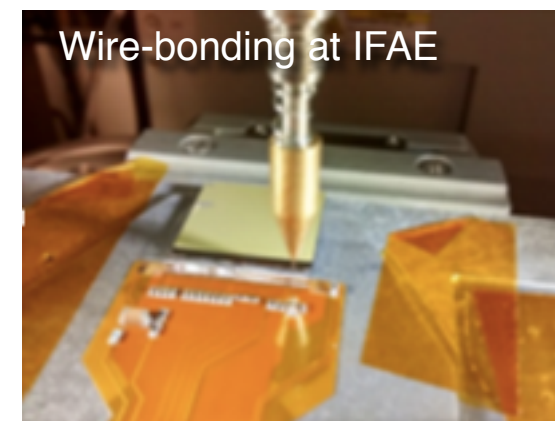
Carrier card



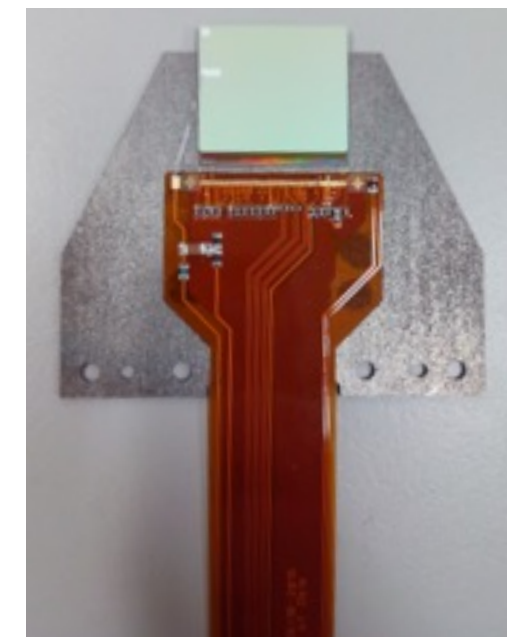
Flex



Pick and Place machine



Wire-bond machine

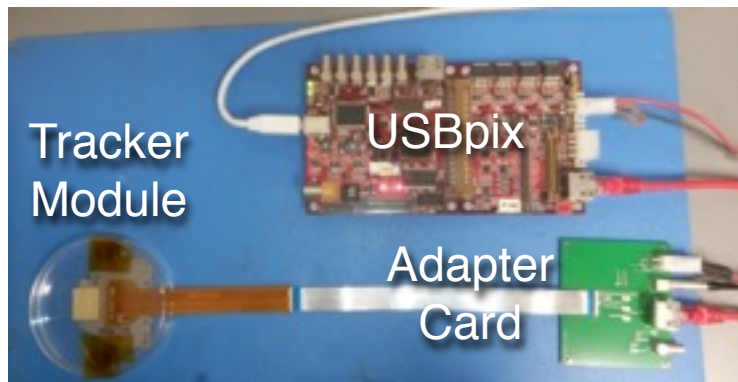
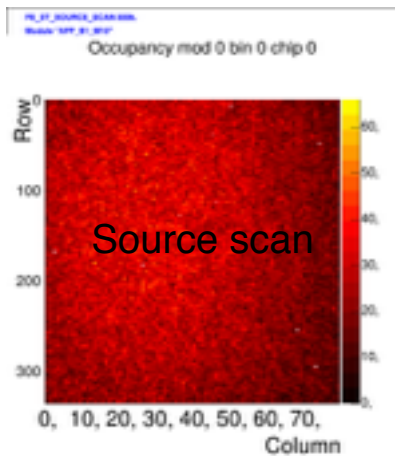
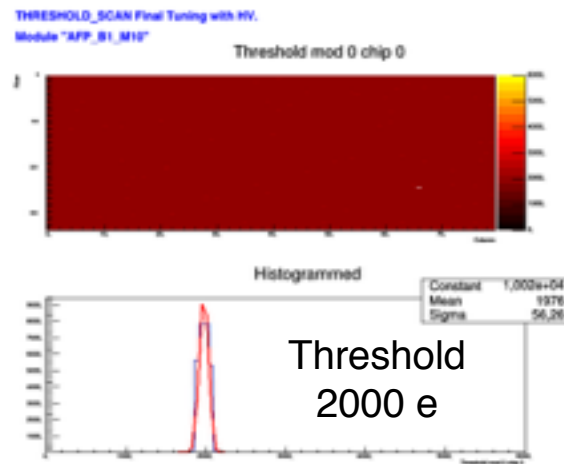
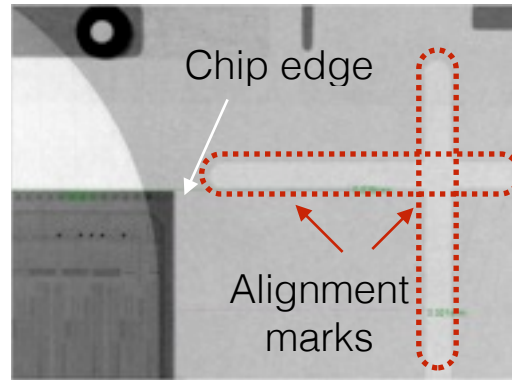


Tracker module

Tracker Module Quality Assurance

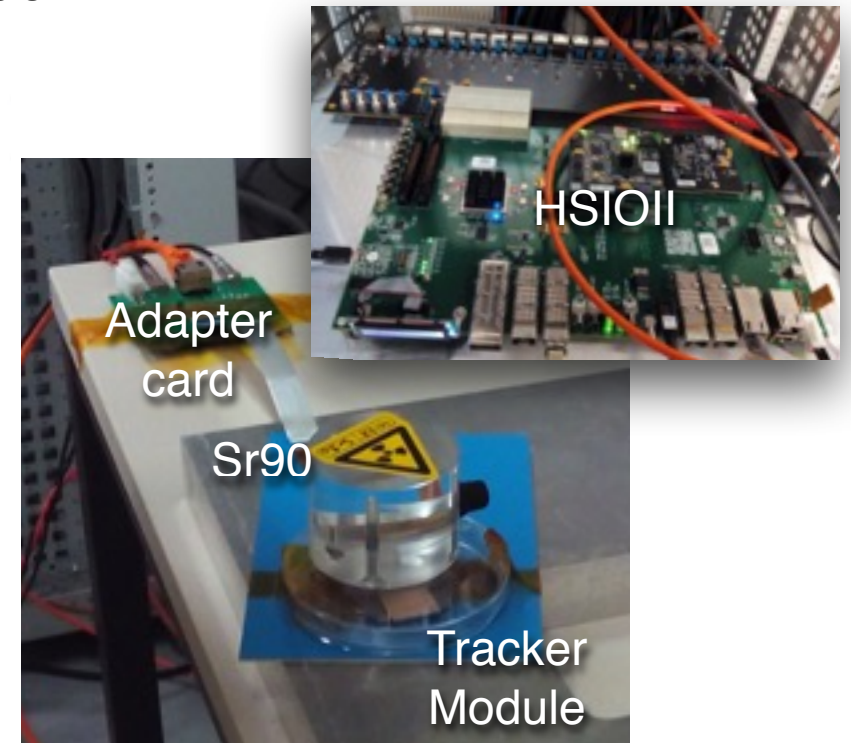
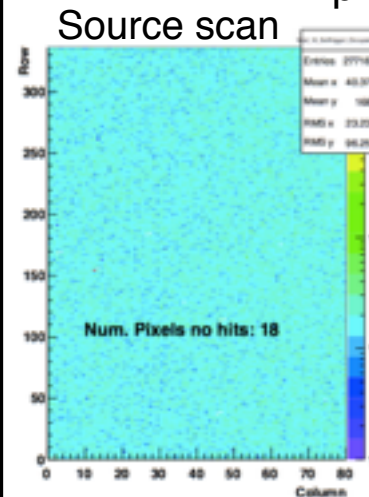
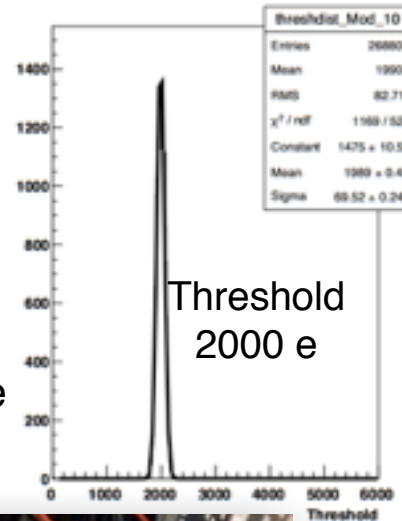
At IFAE-Barcelona

- Alignment measurement with X-ray microscope
- Module testing
 - First tuning and tests with radioactive source to look for disconnected pixels
- Modules are sent to CERN



At CERN (by IFAE)

- Visual inspection
- Module testing with final DAQ system
 - Tuning and tests with radioactive source to look for disconnected pixels

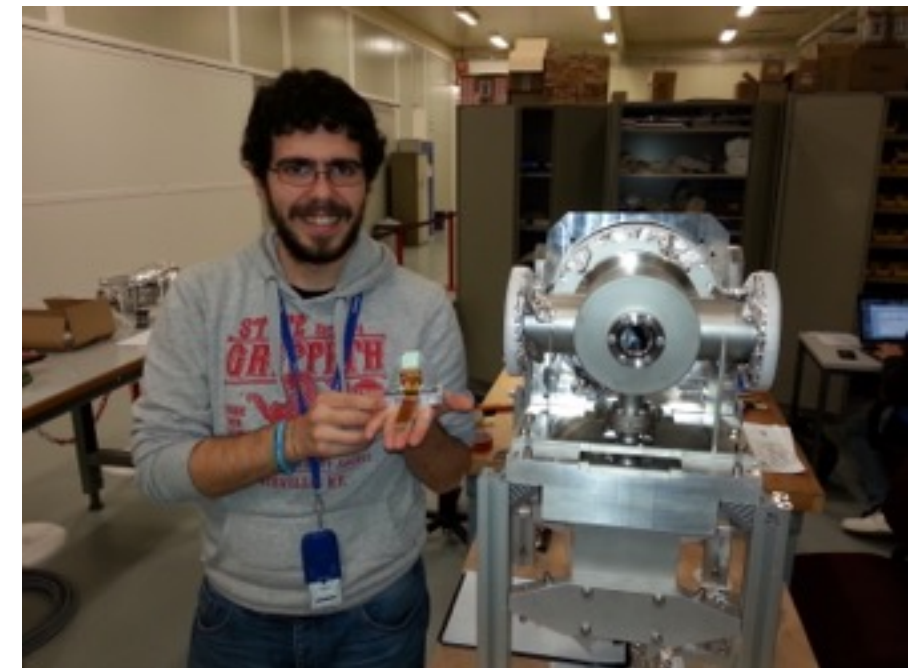
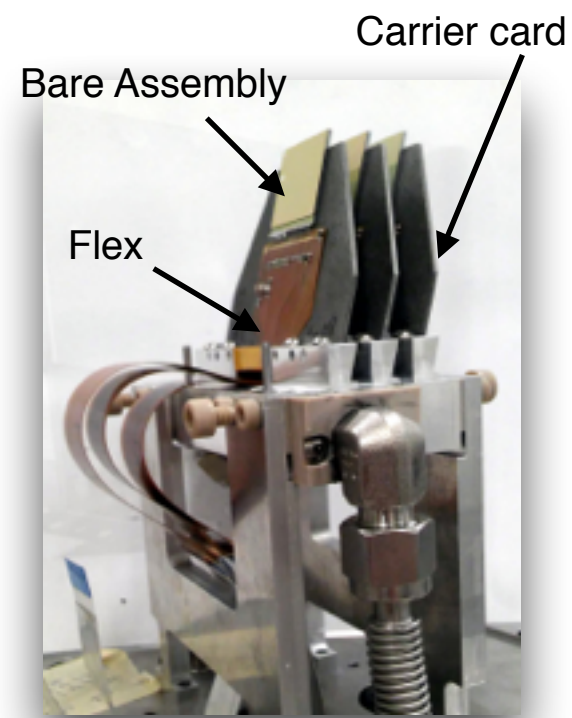


Production Step	Total	Good	Yield
QA	17	14	82 %

Note: includes modules produced after installation

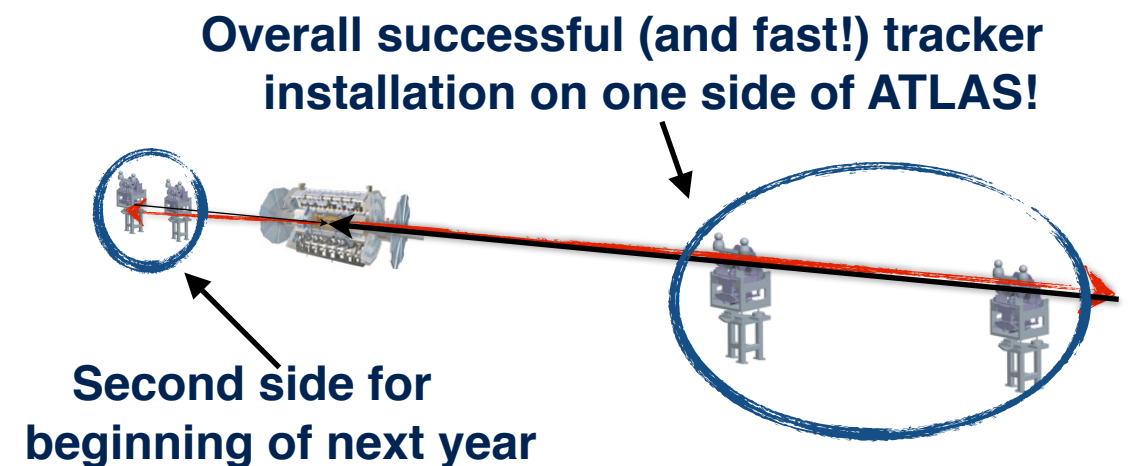
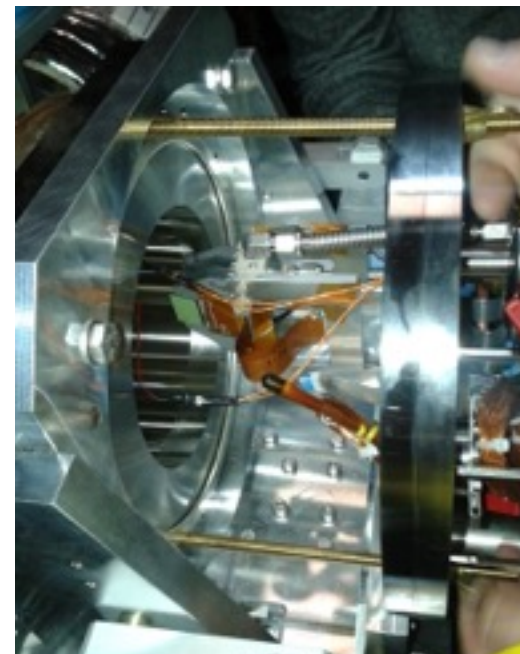
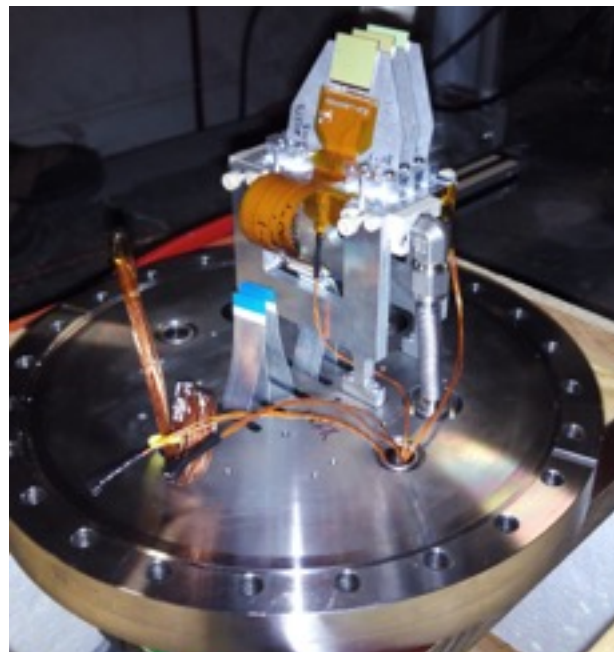
Silicon tracker installation (AFP0+2)

- By December 2015 the installation of the silicon tracker on one side of ATLAS was foreseen for summer 2016
- Still, were **able to produce 7 working modules ahead of time for installation** (26th of February 2016)

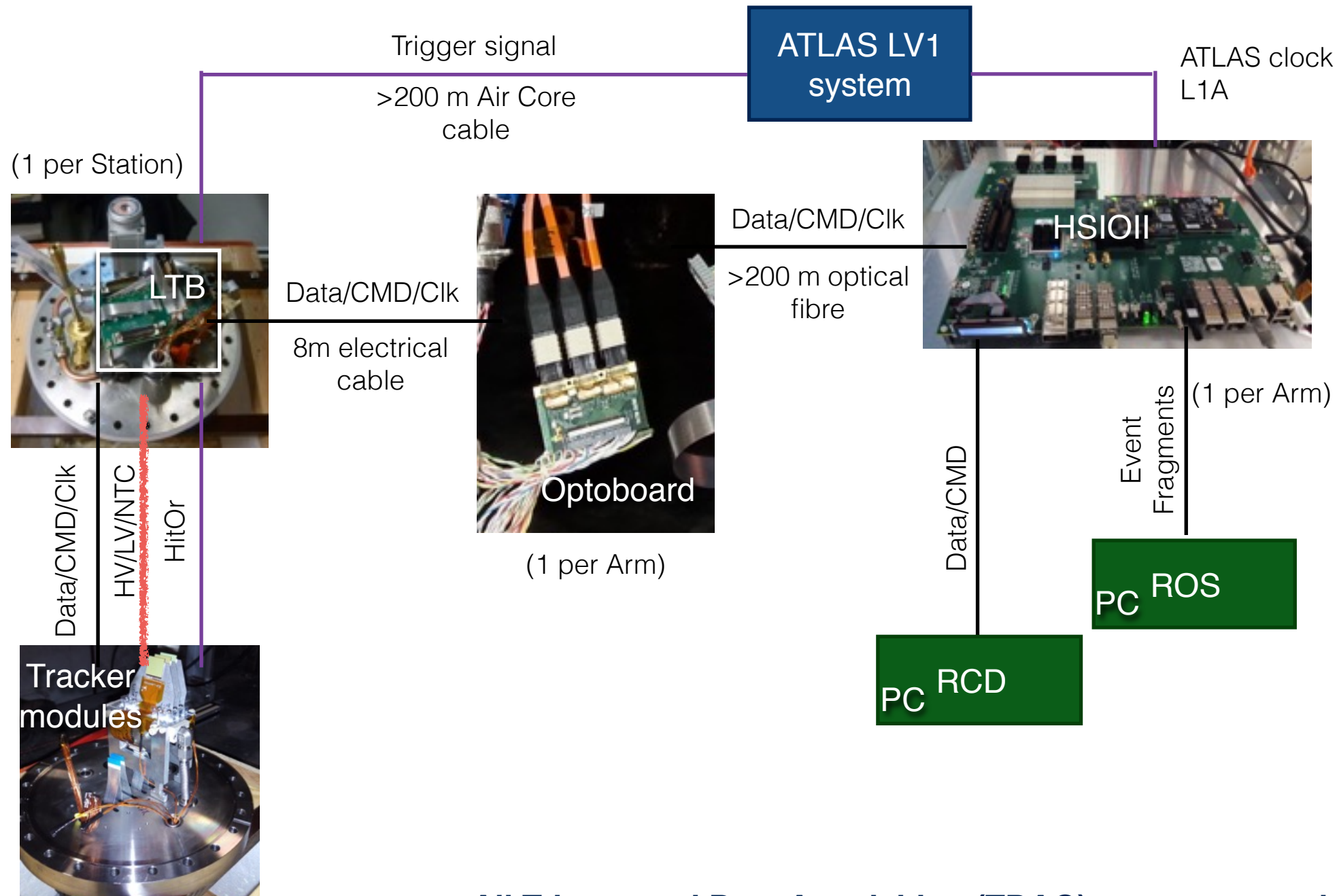


Silicon tracker installation (AFP0+2)

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- Still, were **able to produce 7 working modules ahead of time for installation** (26th of February 2016)
 - 4 (3) modules in C side FAR (NEAR) station
 - Short in HV line of one FAR station module prevents it from being biased
 - Still usable at 0 V: just with lower efficiency

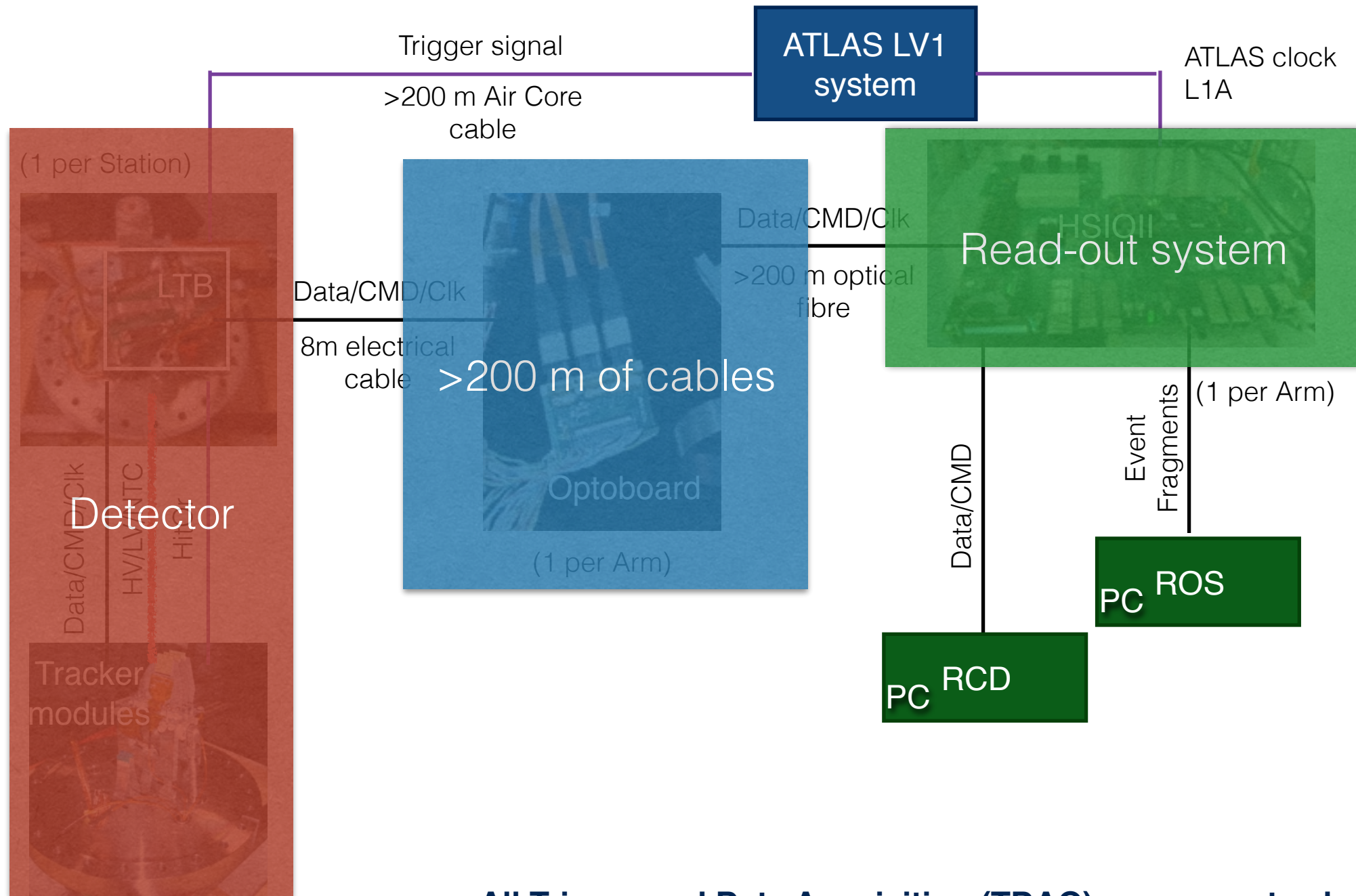


Read-out and trigger chain (AFP0+2)



All Trigger and Data Acquisition (TDAQ) components also installed

Read-out and trigger chain (AFP0+2)



All Trigger and Data Acquisition (TDAQ) components also installed

AFP0+2 running: First insertion & intensity ramp-up (part 1)

Date	Fills with AFP inserted	TDAQ Mode
19-22 April	Alignment and Loss Maps	AFP only
23 April	3 bunches	AFP only
24-25 April	12 bunches	AFP only

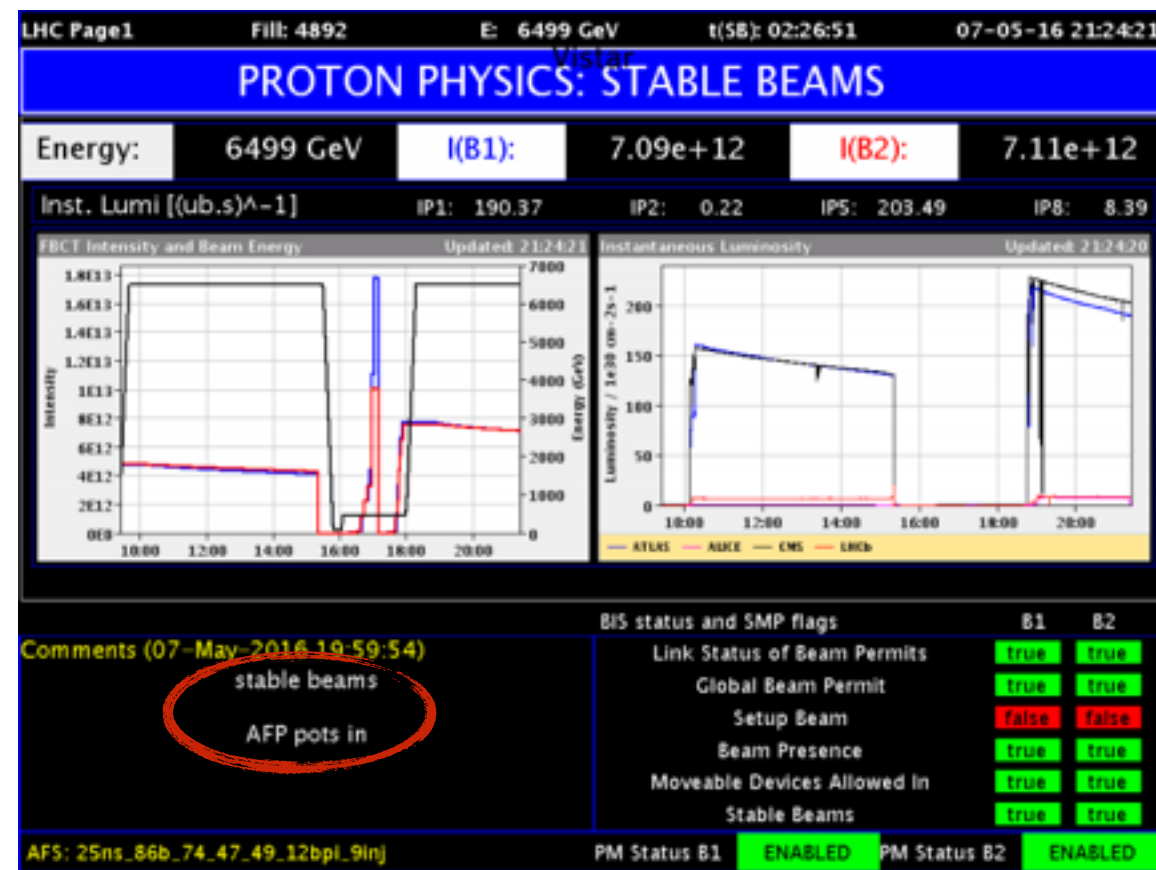
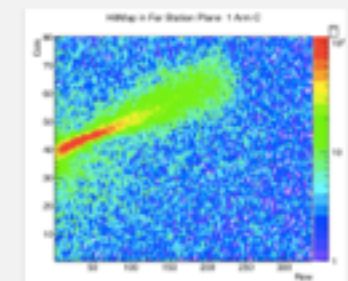
IFAE Internal Newsletter #30

Wednesday, 27th of April 2016

...

AFP commissioning work at CERN: hit map of the first data taking in the beam

The AFP detector was recently installed in the LHC beam line. The sensors installed inside the Roman Pots were produced at CNM-Barcelona and assembled and qualified at IFAE. The 18th of April, the AFP detector was inserted into the LHC beam for the first time, during its beam-based alignment and loss maps tests. I. Lopez and J. Lange are leading the AFP commissioning work at CERN.



First time AFP was inserted in beam position

LHC needs AFP to be inserted for validation during the intensity ramp-up after YETS

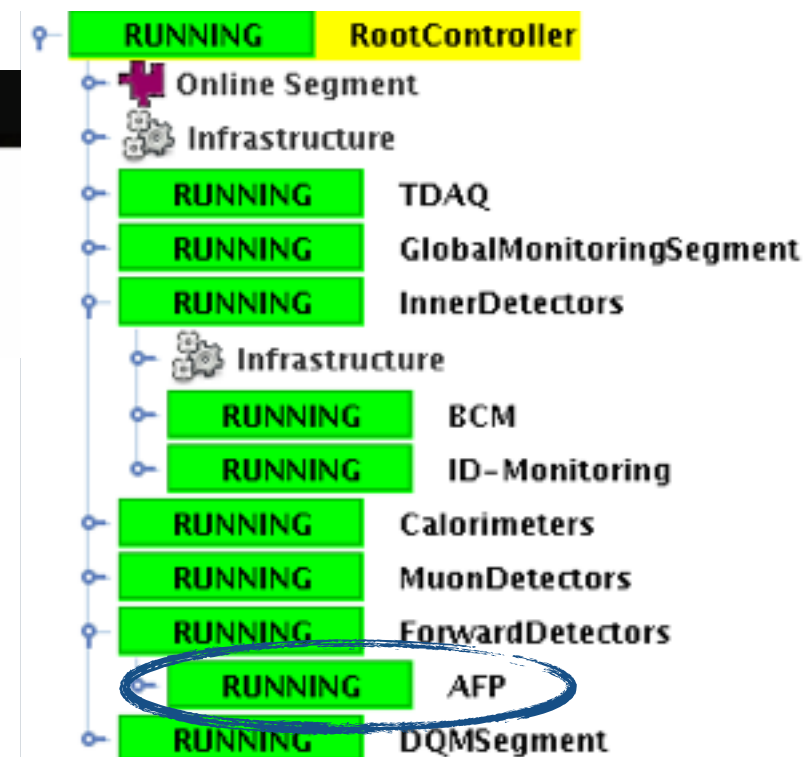
AFP0+2 running: Weasel break and integration

Date	Fills with AFP inserted	TDAQ Mode
19-22 April	Alignment and Loss Maps	AFP only
23 April	3 bunches	AFP only
24-25 April	12 bunches	AFP only
29 April – 5 May	LHC power cut -> TDAQ integration	



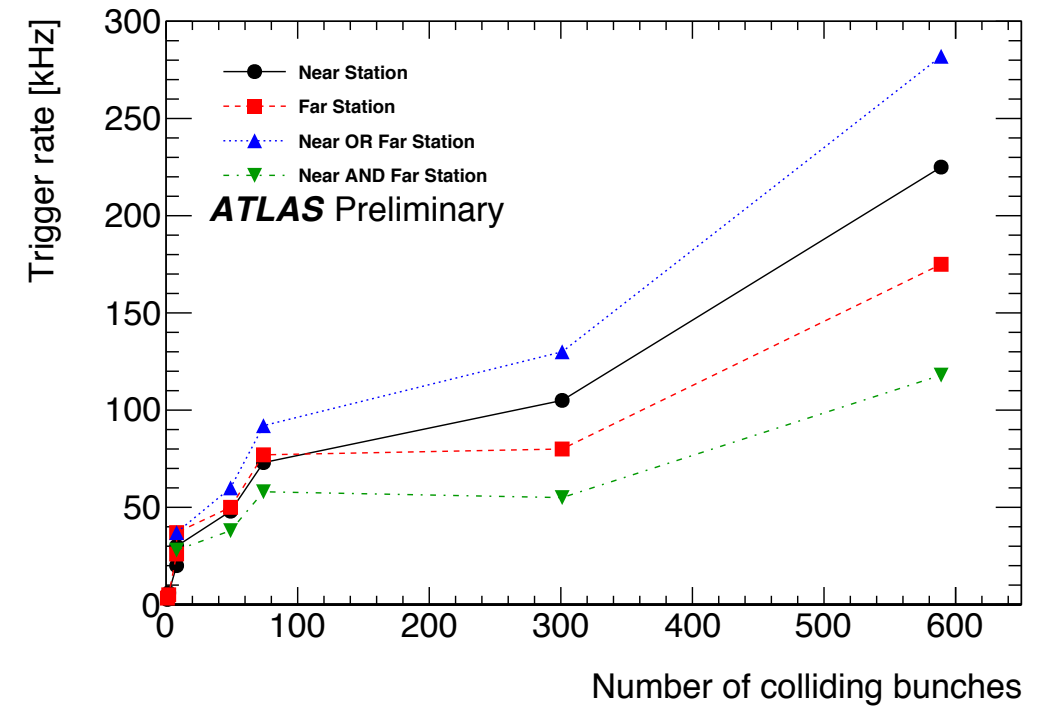
Weasel knocks out CERN's powerful particle accelerator

Integrated AFP Data Acquisition into ATLAS
 —> Can take data combined together with ATLAS



AFP0+2 running: Intensity ramp-up (part 2)

Date	Fills with AFP inserted	TDAQ Mode
19-22 April	Alignment and Loss Maps	AFP only
23 April	3 bunches	AFP only
24-25 April	12 bunches	AFP only
29 April – 5 May	LHC power cut -> TDAQ integration	
7 May	49/86 bunches	with ATLAS
9 May	300 bunches	with ATLAS
13 May	600 bunches	with ATLAS

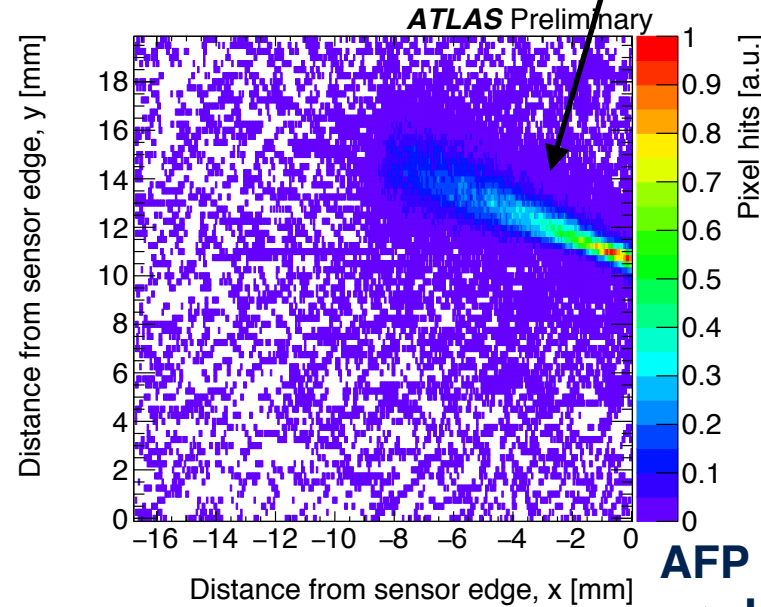
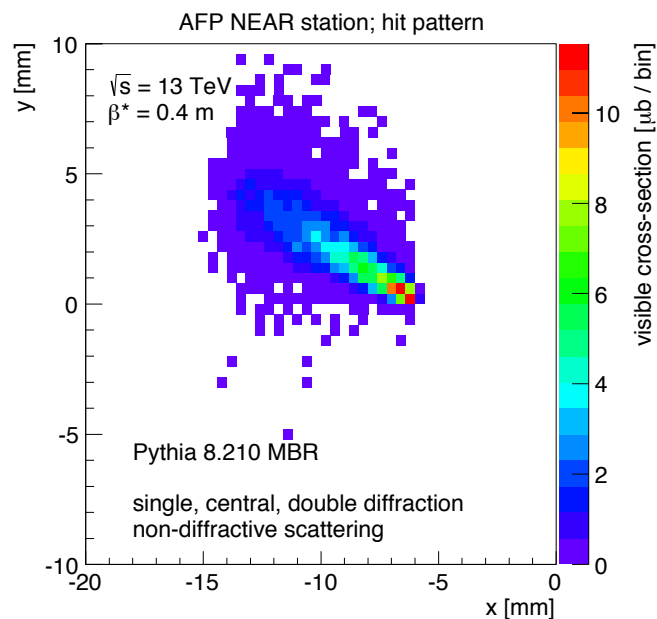


SIMULATION

20 σ nom.
 $\beta=0.40$ m
 $\sqrt{s} = 13$ TeV

DATA

Diffractive protons

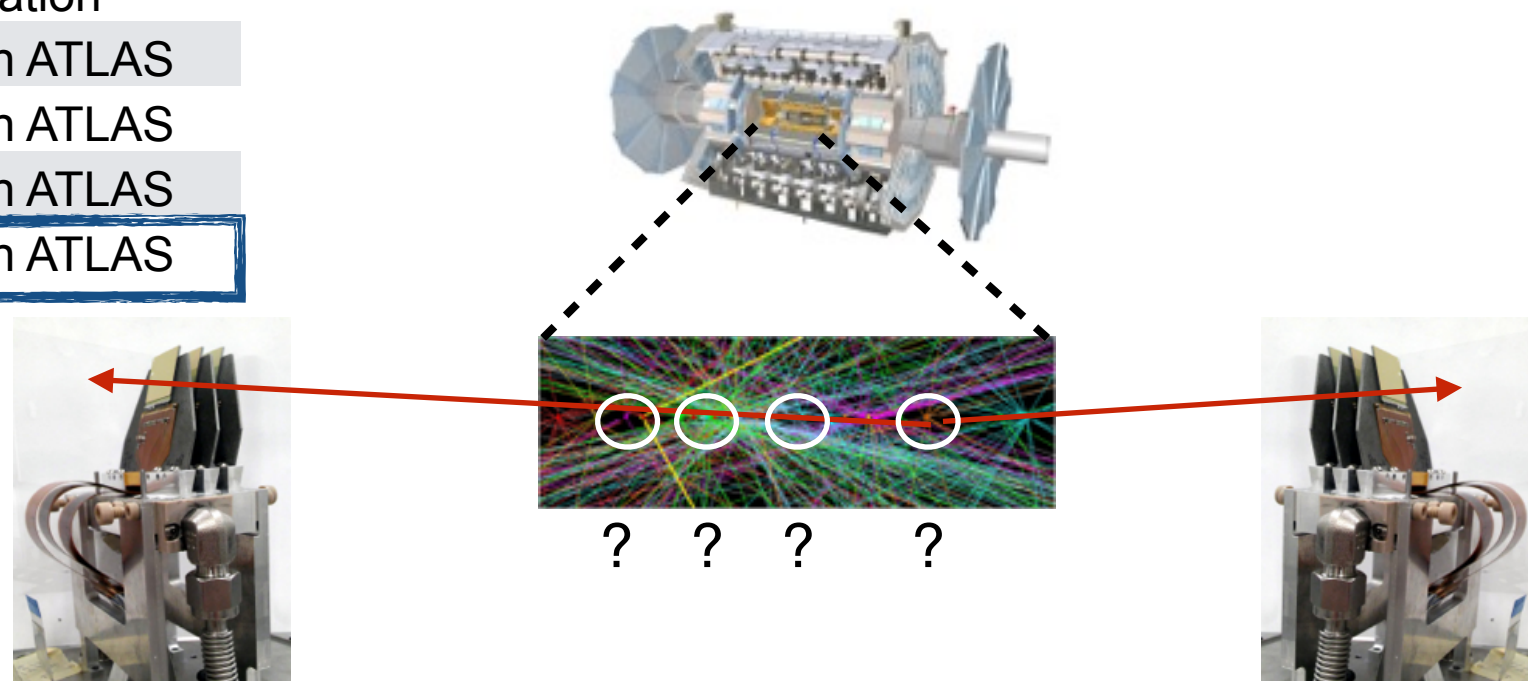


**AFP increases radiation intake on other forward detector
 → Limited in-beam time before AFP destroys it**

AFP0+2 running: Low pile-up physics run

Date	Fills with AFP inserted	TDAQ Mode
19-22 April	Alignment and Loss Maps	AFP only
23 April	3 bunches	AFP only
24-25 April	12 bunches	AFP only
29 April – 5 May	LHC power cut -> TDAQ integration	
7 May	49/86 bunches	with ATLAS
9 May	300 bunches	with ATLAS
13 May	600 bunches	with ATLAS
31 July	600 b. low- μ physics run	with ATLAS

Now the physics!



Without Time-of-Flight can't cope with pile-up -> beam separation to reduce pile-up
 -> AFP's special run at low pile-up coming the 31st of July for physics

To Be Continued

Conclusions and Outlook

Conclusions

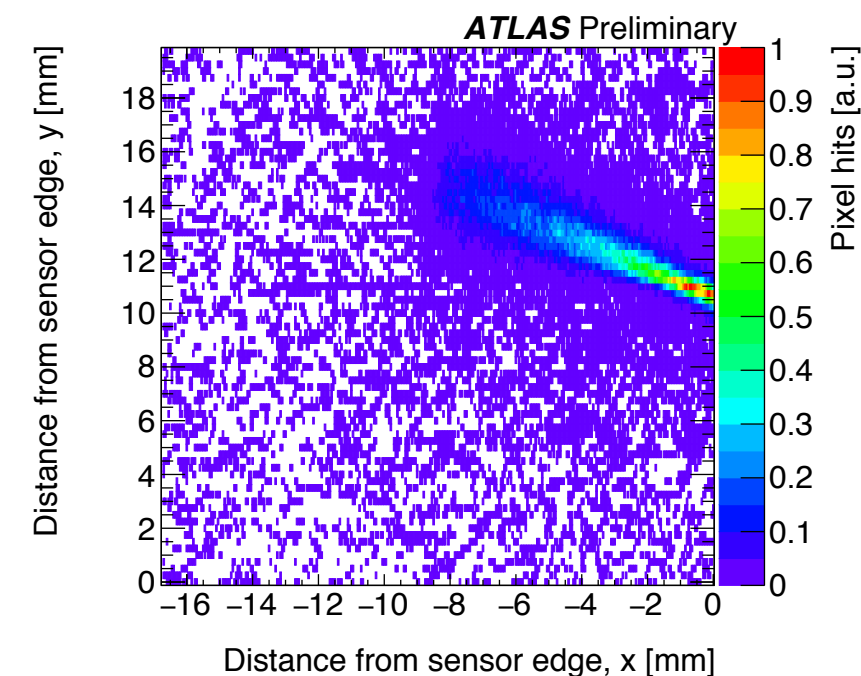
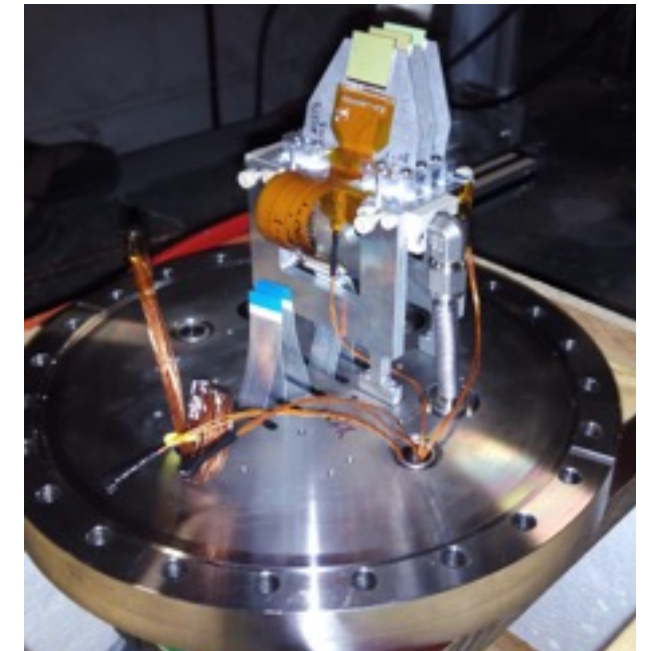
- 3D FE-I4 sensors were proven to be suitable for AFP:
 - Radiation hardness, small inactive area and good position resolution
 - Successful integration test beams with Time-of-Flight detector
- 7 silicon tracker planes were successfully assembled, qualified and installed in AFP0+2 Roman Pots (in a very short time-scale!)
- AFP has been successfully integrated with ATLAS TDAQ and took data during LHC's intensity ramp-up

IFAE crucial for tracker production, beam test coordination, operation and TDAQ integration

Outlook

- New silicon tracker production on-going -> Better quality than first production
- Plan to replace installed modules with new production sensors during EYETS 2016-2017 and install the second AFP arm (AFP2+2)

**Low pile-up for physics run scheduled for this Sunday
Plan to have a first look at the data**



Back-up
